

N-CHANNEL SILICON POWER MOSFET

F-II SERIES

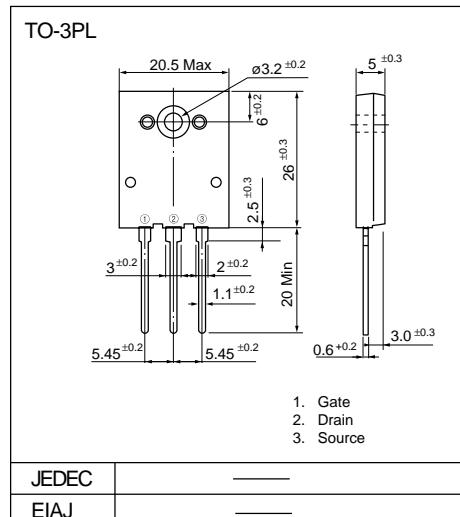
■ Features

- High current
- Low on-resistance
- No secondary breakdown
- Low driving power
- High voltage
- $V_{GSS} = \pm 30V$ Guarantee

■ Applications

- Switching regulators
- UPS
- DC-DC converters
- General purpose power amplifier

■ Outline Drawings

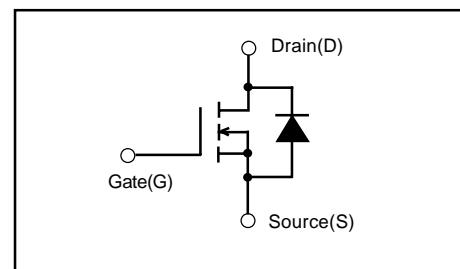


■ Maximum ratings and characteristics

● Absolute maximum ratings (T_c=25°C unless otherwise specified)

Item	Symbol	Rating	Unit
Drain-source voltage	V _{DS}	500	V
Continuous drain current	I _D	30	A
Pulsed drain current	I _{D(puls)}	92	A
Continuous reverse drain current	I _{DR}	30	A
Gate-source peak voltage	V _{GS}	±30	V
Max. power dissipation	P _D	300	W
Operating and storage temperature range	T _{ch}	+150	°C
	T _{tstg}	-55 to +150	°C

■ Equivalent circuit schematic

● Electrical characteristics (T_c=25°C unless otherwise specified)

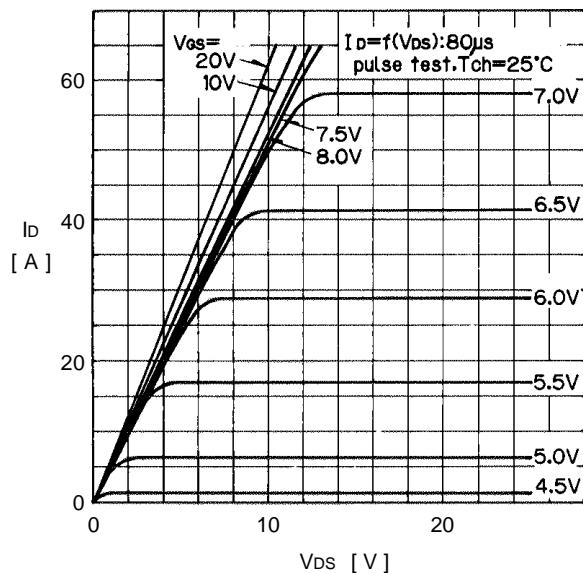
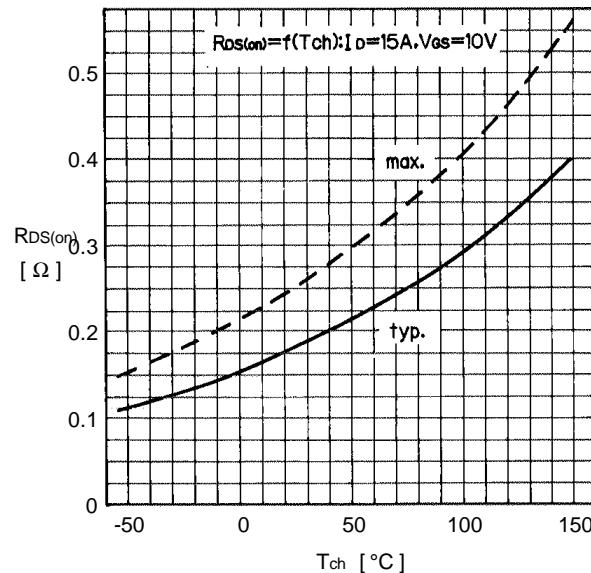
Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D =1mA V _{GS} =0V	500			V	
Gate threshold voltage	V _{GS(th)}	I _D =1mA V _{DS} =V _{GS}	2.5	3.5	5.0	V	
Zero gate voltage drain current	I _{DSS}	V _{DS} =500V V _{GS} =0V	T _{ch} =25°C T _{ch} =125°C	10 0.2	500 1.0	μA mA	
Gate-source leakage current	I _{GSS}	V _{GS} =±30V V _{DS} =0V		10	100	nA	
Drain-source on-state resistance	R _{DS(on)}	I _D =15A V _{GS} =10V		0.18	0.25	Ω	
Forward transconductance	g _f	I _D =15A V _{DS} =25V	10.0	20.0		S	
Input capacitance	C _{iss}	V _{DS} =25V		4200	6300	pF	
Output capacitance	C _{oss}	V _{GS} =0V		600	900		
Reverse transfer capacitance	C _{rss}	f=1MHz		280	420		
Turn-on time t _{on} (t _{on} =t _{d(on)} +t _r)	t _{d(on)} t _r	V _{CC} =300V R _G =25Ω		60	90	ns	
Turn-off time t _{off} (t _{off} =t _{d(off)} +t _f)	t _{d(off)} t _f	I _D =30A		300	450		
Diode forward on-voltage	V _{SD}	V _{GS} =10V		600	900		
Reverse recovery time	t _{rr}	I _F =2xI _{DR} V _{GS} =0V T _{ch} =25°C		300	450		
		I _F =I _{DR} di/dt=100A/μs T _{ch} =25°C			1.10	1.7	V
					600		ns

● Thermal characteristics

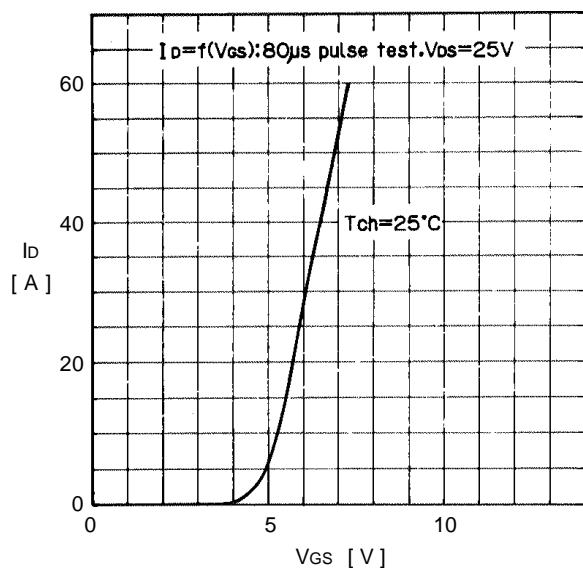
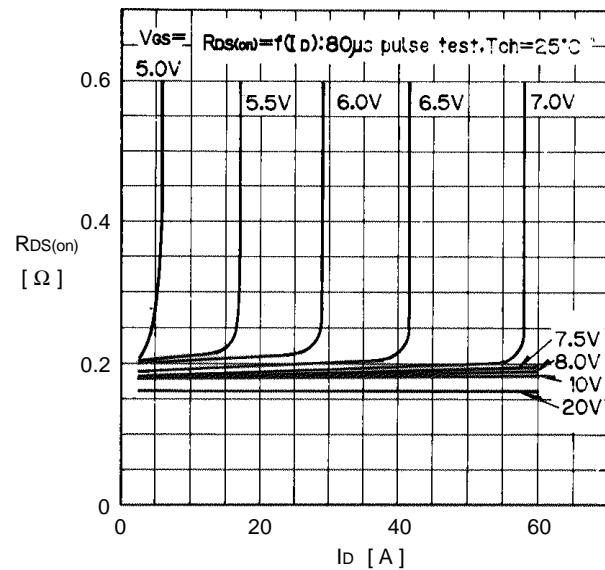
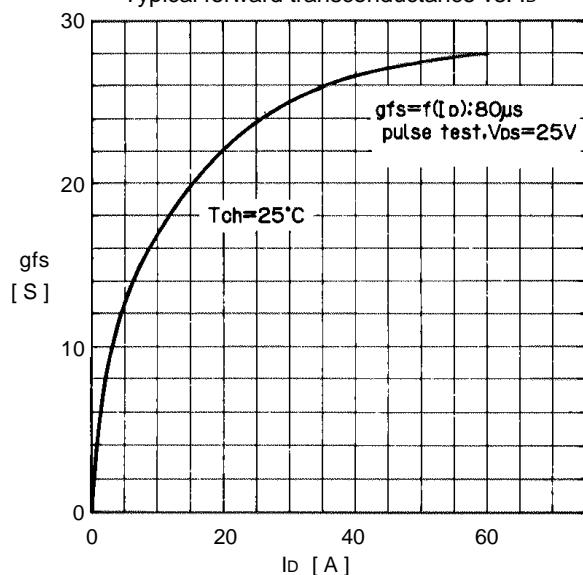
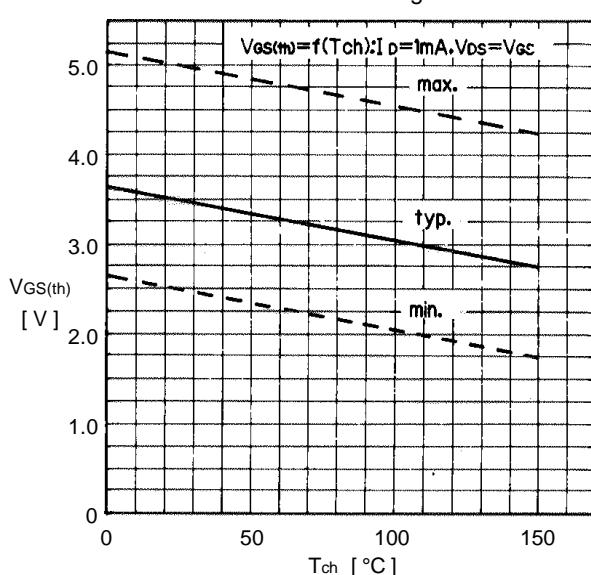
Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	R _{th(ch-a)} R _{th(ch-c)}	channel to ambient channel to case				°C/W

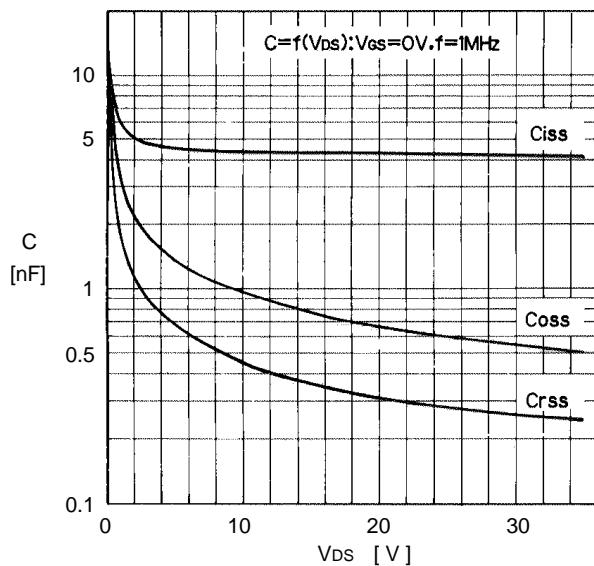
■ Characteristics

Typical output characteristics

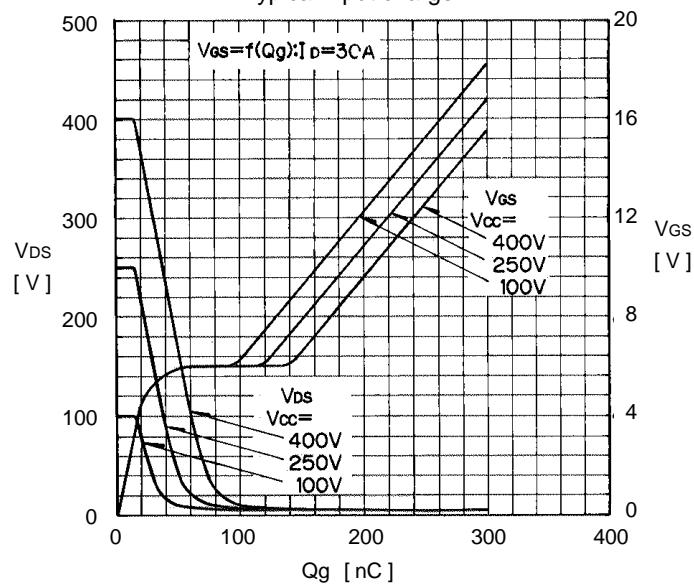
Drain-Source on state resistance vs. T_{ch} 

Typical transfer characteristics

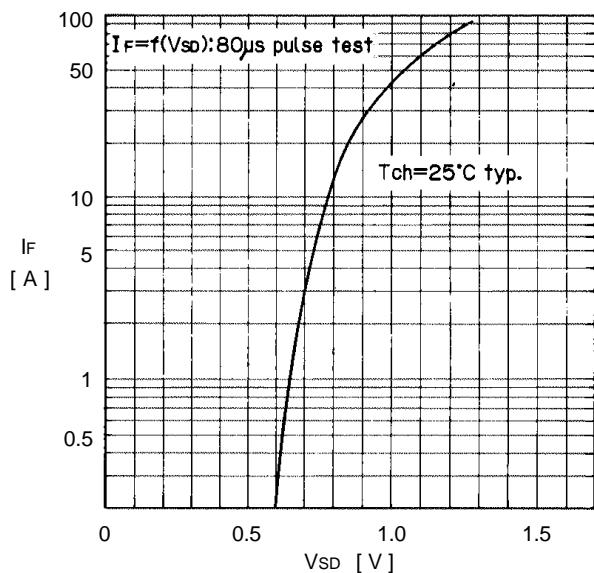
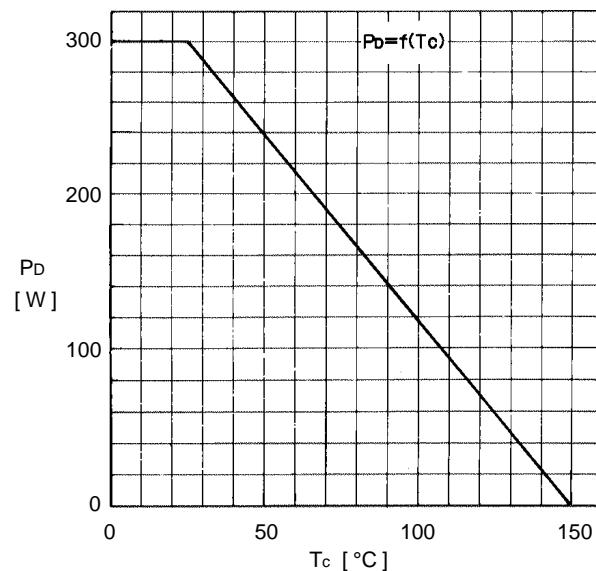
Typical Drain-Source on state resistance vs. I_D Typical forward transconductance vs. I_D Gate threshold voltage vs. T_{ch} 

Typical capacitance vs. V_{DS}

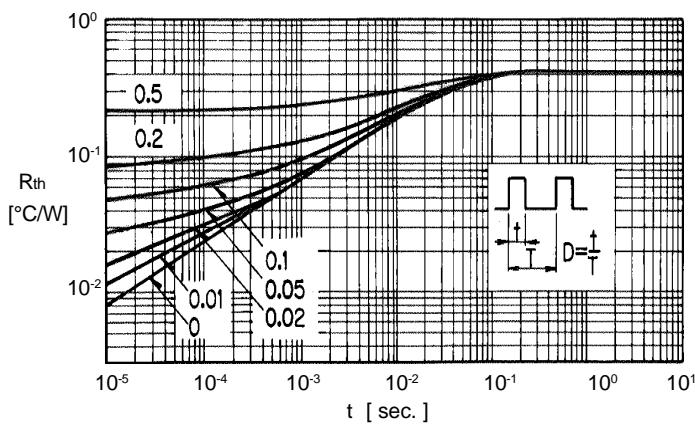
Typical input charge



Forward characteristics of reverse diode

Allowable power dissipation vs. T_c

Transient thermal impedance



Safe operating area

